S-Bond Technologies, LLC



S-Bond 220 Active Solder Joining of Metals

An ACTIVE SOLDER...

- Joins any material, versatile
- Wets metals and ceramic alike
- Eliminates need for flux
- Joins in air
- No pre-plating required
- Cost effective
- Environmentally friendly material

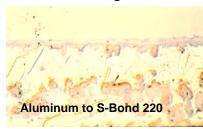
What is S-Bond[®] 220?

S-Bond 220 is a solder material (Sn-Ti-Ag) and a process by which most materials, including dissimilar metallic and ceramic materials can be joined. It is a new family of solders, developed and patented by S-Bond Technologies. The material is an activated solder with elements added to the alloy that react with surfaces during joining and adhere to any surface films that disrupt normally wetting and bonding. The characteristics of S-Bond 220 include:

- Joining Temperature(s):
 - 250 270°C (480 580°F)
- Tensile Strengths:
 - >28-100 MPa (4,100 7,000 psi)

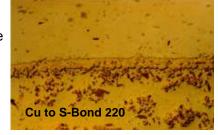
Our investigations to date indicate the versatility of S-Bond 220, with examples shown in this Bulletin:

Aluminum Joining



- Wets aluminum
- Clean interfaces
- Excellent bonds
- Joins at ~250 °C

- Wets allovs
- Excellent interface
- Good conductivity
- Good thermal properties



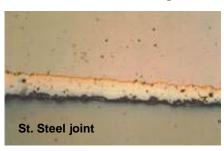
Titanium Joining



- Joins in air
- No interface oxides
- Excellent interfaces
- Good strength
- Ti-alloy compatible

Stainless Steel Joining

- No vacuum
- Excellent interface
- No brittle phases
- No pre-cleaning
- No pre-plating



Stainless Steel to **Aluminum**

- Compatible
- No premetallization
- Low Temperature
- Good toughness

Other Joined Metals include...

- Cast Iron Stellite - Superalloys - Tantalum - Beryllium - Magnesium

Applications

Sheet/Tube

- Heat exchangers Coolers
- Sports equipment - Appliances
- Condensers - Probes

Structures

- Food processing
- Aircraft frames
- Auto components Truck/frames
- Rail cars - Nacelles
- Cargo structures

- Acoustic suppression

Electrical

- Buss bars
- Motor/magnets
- Lighting connectors Conductors/connectors
- Appliances
- Power electronics